

IEC QUALITY ASSESSMENT SYSTEM (IECQ)

covering Electronic Components, Assemblies, Related Materials and Processes

For rules and details of the IECQ visit www.iecq.org

Schedule of Scope to Certificate of Conformity Approved Component - Capability

IECQ Certificate No.: IECQ-C BSI 13.0001
CB Certificate No.: 030/ICA

Schedule Number: IECQ-C BSI 13.0001-S Rev No.: 6 Revision Date: 2024/01/31 Page 1 of 2

Board Types: Rigid Multilayer (Type 4)

IPC 6012E Class 3*

Rigid double-sided with plated through holes (Type 2)

Rigid single & double-sided with plain holes (Types 1 & 2)

Double-Sided boards (Type 2) Single-Sided Boards (Type 1 & 2)

Flex-Rigid multilayer with through holes (Type 4)

IPC 6013D Class 3*

Base Materials: Epoxide Woven Glass (IPC 4101, IPC 4202, IPC 4203,

BS 4584)

Polyimide film/polyester film (IPC 4204) Polytetrafluorethylene (IPC 4103)

Board Size: 495.30 mm x 419.10 mm single/double and multilayer

261.87 mm x 322.33 mm flex-rigid multilayer

Number of32 maximumRigid multilayerLayers:10 maximumFlex-Rigid multilayer

Conductors: 0.10 mm (photomech) Tolerance -0.02 +0.03 mm

Plated-through 0.20 mm Minimum Finished hole size **Hole Diameter:** 0.80 mm Minimum Finished hole size

Aspect Ratio: 20:1 Maximum single and double sided

16.0:1 Maximum multilayer

2.27 : 1 Maximum flex-rigid multilayer

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Finishes: * Hot Air Solder Levelling

Immersion Silver

2.5µm Gold over Copper Edge Contacts Liquid Photopolymer Solder Resist

Legend; UV or Oven Cured Solder resist UV cured

Additional: Selective Electroplated Nickel / Gold (2.5 µm) on Copper

Selective Electroless Nickel / Gold (0.05 μ m) on Copper

Immersion Silver, Organic Coating

Nema LI 1

* This finish meets the solderability requirements.

